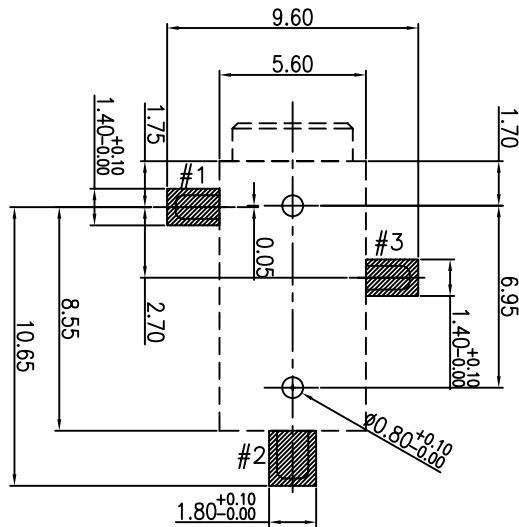
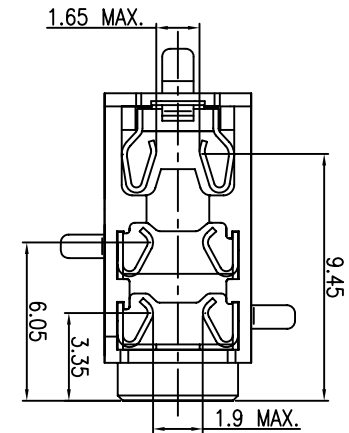
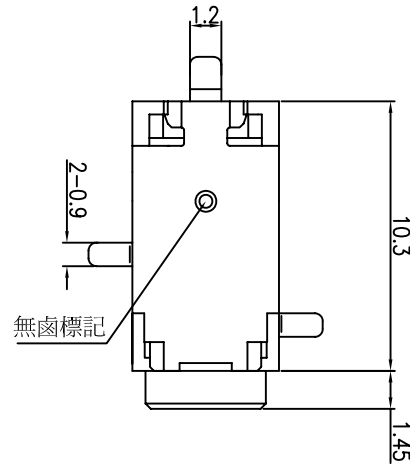
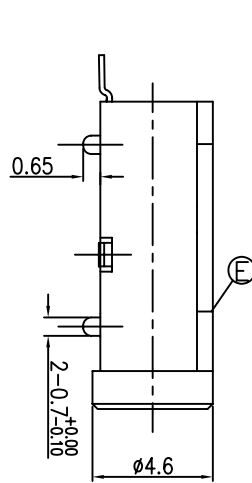
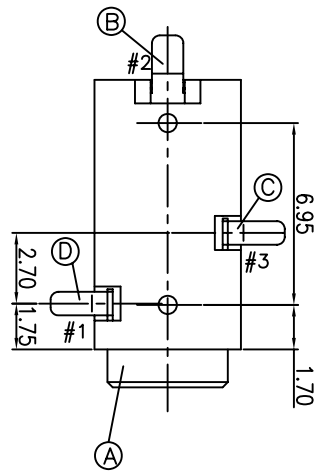
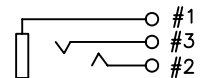
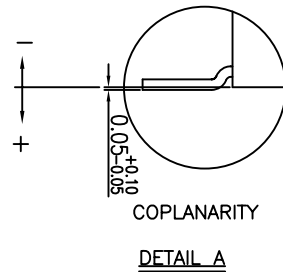
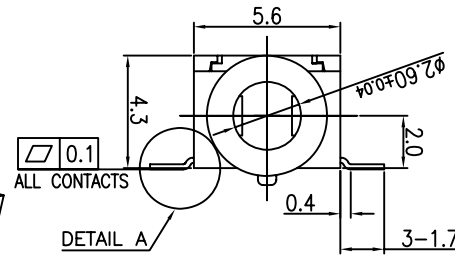
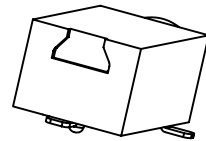


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
E	無鹵導入 ECN NO: T080204	宋軍華	2008.11.27
F	客戶需求 ECN NO: C090117	ARES	2010.03.15



PCB LAYOUT TOLERANCE ±0.05  
PRINTED SIDE



SPECIFICATIONS:

- SEE 2SJ-0259 SERIES PHONE JACKS SPECIFICATION.
- PACKING: TAPE & REEL
- TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- SOLDER HEAT RESISTANCE REFLOW SOLDERING 260°C 10SECS.
- DATE CODE: YY MM DD  
Day  
Month  
Year

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	COVER	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK COLOR
D	EARTH TERMINAL	1	COPPER ALLOY 0.2t	GOLD FLASH
C	RING TERMINAL	1	COPPER ALLOY 0.2t	GOLD FLASH
B	TIP SPRING	1	COPPER ALLOY 0.2t	GOLD FLASH
A	BODY	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: ANGLES:		TITLE: 2.5Ø PHONE JACK		
X	:±0.5	X	:±2°	DWN ARES PART NO. 2SJ-0259-005
X.X	:±0.3	X.X	:±1°	CHKD MUYUAN SCALE 5:1 UNIT: mm
X.XX	:±0.2	APVD ROBIN SIZE: A3 SHEET: 10F1 REV: F		
<b>CUSTOMER COPY</b>				